

Amendments to the Claims

This listing of claims replaces all prior versions, and listings, of claims in the above-identified application:

Listing of Claims

1-62. (CANCELED)

63. (Currently Amended) A singulation method comprising:

providing a circuit board substrate assembly comprising a substrate material having first and second opposed edges, the substrate material comprising:

a plurality of circuit forming regions comprising at least one pair of adjacent circuit forming regions;

a first interconnection region and a second interconnection region, wherein the first interconnection region extends along the first edge and is located between the first edge and the plurality of circuit forming regions, wherein the second interconnection region extends along the second edge and is located between the second edge and the plurality of circuit forming regions; and

at least one opening defined in the substrate material between each pair of adjacent circuit forming regions, wherein the at least one opening extends into at least portions of both the first interconnection region and second interconnection region;

removing at least a portion of the first and second interconnection regions along a respective first and second singulation axis defined therein parallel to one another to singulate at least two circuit forming regions of the plurality of circuit forming regions, the first singulation axis and the second singulation axis intersecting with the at least one opening defined between each pair of adjacent circuit forming regions.

64. **(ORIGINAL)** The method of claim 63, wherein removing at least a portion of the first and second interconnection regions comprises moving a singulation tool along the first singulation axis and the second singulation axis.

65. **(ORIGINAL)** The method of claim 64, wherein moving a singulation tool along the first singulation axis and the second singulation axis comprises moving a routing tool along the first singulation axis and the second singulation axis.

66. **(ORIGINAL)** A singulation method comprising:

providing a circuit board substrate assembly comprising a substrate material, wherein the substrate material comprises a plurality of rows of circuit forming regions lying along a length of the substrate material, wherein each row comprises at least one pair of adjacent circuit forming regions, wherein a singulation axis is defined between each pair of adjacent rows, wherein at least one pair of adjacent circuit forming regions in at least one row is separated by at least one opening defined in the substrate material that intersects with a singulation axis defined between the at least one row and an adjacent row, and that further intersects with a singulation axis defined between the at least one row and another adjacent row; and

removing at least a portion of each of the plurality of interconnection regions along each of the plurality of singulation axes to singulate the at least two circuit forming regions of the plurality of rows of circuit forming regions.

67. **(ORIGINAL)** The method of claim 66, wherein removing at least a portion of the substrate material comprises moving a singulation tool along each of the singulation axes.

68. **(ORIGINAL)** The method of claim 67, wherein moving a singulation tool along each of the singulation axes comprises moving a routing tool along each of the singulation axes.